



SKYWORKS®

DATA SHEET

SKY77761-11 Power Amplifier Module for CDMA/ WCDMA/ HSDPA/ HSUPA/ HSPA+ Band I (1920–1980 MHz)

Applications

- WCDMA handsets
- HSDPA
- HSUPA
- HSPA+
- CDMA2000
- EVDO

Features

- Low voltage positive bias supply 3.0 V to 4.5 V
- Good linearity
- High efficiency
 - 48% at 28.25 dBm
- Large dynamic range
- Small, low profile package
 - 3 mm x 3 mm x 0.9 mm
 - 10-pad configuration
- Power down control
- InGaP
- Supports low collector voltage operation
- Digital Enable
- No V_{REF} required
- CMOS compatible control signals
- Integrated Directional Coupler

Description

The SKY77761-11 Power Amplifier Module (PAM) is a fully matched 10-pad surface mount module developed for Wideband Code Division Multiple Access (WCDMA) applications. This small and efficient module packs full 1920–1980 MHz bandwidth coverage into a single compact package. Because of high efficiencies attained throughout the entire power range, the SKY77761-11 delivers unsurpassed talk-time advantages. The SKY77761-11 meets the stringent spectral linearity requirements of High Speed Downlink Packet Access (HSDPA), and High Speed Uplink Packet Access (HSUPA) data transmission with high power added efficiency. An integrated directional coupler eliminates the need for any external coupler.

The Gallium Arsenide (GaAs) Microwave Monolithic Integrated Circuit (MMIC) contains all amplifier active circuitry, including input and interstage matching circuits. The silicon CMOS support die, providing precision biasing for the MMIC affords a true CMOS-compatible control interface. Output match into a 50-ohm load, realized off-chip within the module package, optimizes efficiency and power performance.

The SKY77761-11 is manufactured with Skyworks' InGaP GaAs Heterojunction Bipolar Transistor (HBT) process which provides for all positive voltage DC supply operation and maintains high efficiency and good linearity. While primary bias to the SKY77761-11 can be supplied directly from any suitable battery with an output of 3.2 V to 4.2 V, optimal performance is obtained with VCC2 sourced from a DC-DC power supply adjusted within 0.5 V to 3.6 V based on target output power levels. Power down executes by setting VENABLE to zero volts. No external supply side switch is needed as typical "off" leakage is 1 μ A with full primary voltage supplied from the battery.

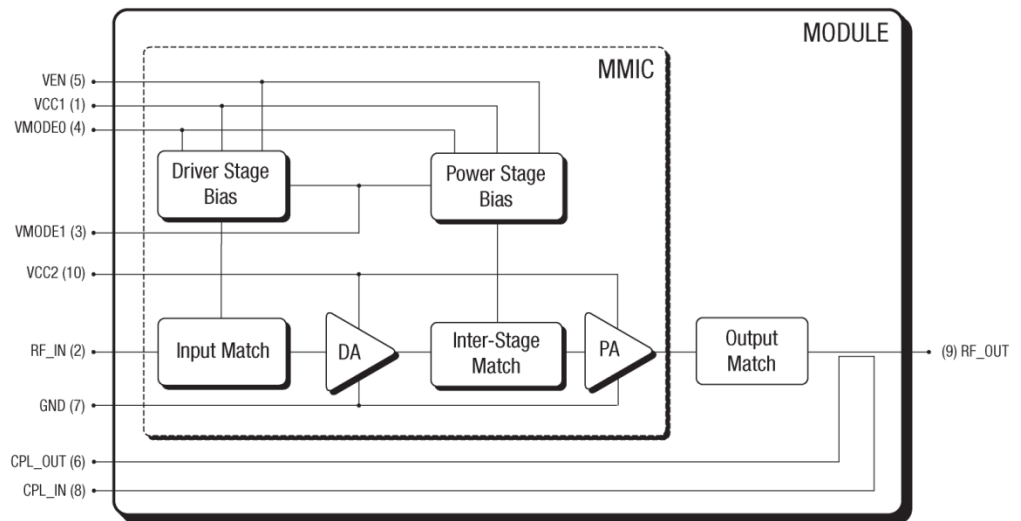
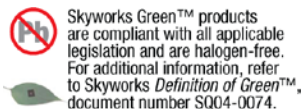


Figure 1. SKY77761-11 Functional Block Diagram

Electrical Specifications

The following tables list the electrical characteristics of the SKY77761-11 Power Amplifier. Table 1 lists the absolute maximum ratings and Table 2 shows the recommended operating conditions. Electrical specifications for nominal operating

conditions are listed in Table 4. Table 3 presents a truth table for the power settings. Tables 5 through 8 provide the standard test configurations for WCDMA (STC1), HSDPA (STC2), and HSUPA (STC3, STC4) respectively.

Table 1. Absolute Maximum Operating Conditions

No damage assuming only one parameter set at limit at a time with all other parameters set at nominal value.

Parameter	Symbol	Minimum	Nominal	Maximum	Unit
RF Input Power	P _{IN}	—	0	10	dBm
Supply Voltage	No RF V _{CC1}	—	3.4	6.0	Volts
	With RF V _{CC2}	—	—	4.6	
Enable Control Voltage	V _{EN}	—	1.8	4.2	Volts
Mode Control Voltage	V _{MODE0}	—	1.8	4.2	Volts
	V _{MODE1}	—	1.8	4.2	
Case Temperature ¹	Operating T _{CASE}	–30	25	+110	°C
	Storage T _{STG}	–40	—	+150	

¹ Case Operating Temperature (T_{CASE}) refers to the temperature of the GROUND PAD at the underside of the package.

Table 2. Recommended Operating Conditions

Parameter	Symbol	Minimum	Nominal	Maximum	Unit
RF Output Power ¹	WCDMA	P _{OUT_MAX}	—	28.25	dBm
	HSDPA		—	27.25	
	HSUPA		—	24.65	
	CDMA2000 (–30 °C to +50 °C)		—	27.75	
	CDMA2000 (+85 °C)		—	25.75	
Operating Frequency	f ₀	1920	1950	1980	MHz
Supply Voltage ²	V _{CC1}	3.0	3.4	4.5	Volts
	V _{CC2}	0.5	—	3.6	
Enable Control Voltage	Low V _{EN_L}	0.0	0.0	0.5	Volts
	High V _{EN_H}	1.35	1.8	3.1	
Mode Control Voltage	Low V _{MODE0}	0.0	0.0	0.5	Volts
	V _{MODE1}	0.0	0.0	0.5	
	High V _{MODE0}	1.35	1.8	3.1	
	V _{MODE1}	1.35	1.8	3.1	
Case Operating Temperature ³	T _{CASE}	–20	+25	+85	°C

¹ 0.5 dB output power back-off when 3.2 V ≤ V_{CC2} < 3.4 V.

² Specifications in Table 4 are specified at V_{CC1} = 3.2 V–4.2 V.

³ Equivalent to –30 °C to +75 °C Ambient Operating Temperature.

Table 3. Modes of Operation

Power Setting	ENABLE	VMODE0	VMODE1	VCC
Power Down Mode	Low	Low	Low	On
Standby Mode	Low	—	—	On
High Power Mode ($17.0 \text{ dBm} \leq P_{\text{OUT}} \leq 28.25 \text{ dBm}$)	High	Low	—	On
Medium Power Mode ($7.0 \text{ dBm} \leq P_{\text{OUT}} \leq 17.0 \text{ dBm}$)	High	High	Low	On
Low Power Mode ($P_{\text{OUT}} \leq 7.0 \text{ dBm}$)	High	High	High	On

Table 4. Electrical Specifications for Nominal Operating Conditions

Per Table 2 over dynamic range up to 28.25 dBm output power for STC1 modulation, unless otherwise specified.

Characteristics	Symbol	Condition	Minimum	Typical	Maximum	Unit
Gain ⁵	GLOW	$P_{\text{OUT}} = 7.0 \text{ dBm}$ $V_{\text{CC2}} = 0.8 \text{ V}$	12.0	16.0	19.0	dB
	GMED	$P_{\text{OUT}} = 17.0 \text{ dBm}$ $V_{\text{CC2}} = 1.3 \text{ V}$	19.0	23.0	28.0	
	GHIGH	$P_{\text{OUT}} = 28.25 \text{ dBm}$	25.0	28.5	31.0	
Rx Band Gain	RxG	$P_{\text{OUT}} = 7.0 \text{ dBm}$	—	—	−1	dB
	RxG_GPS	$P_{\text{OUT}} = 17.0 \text{ dBm}$	—	—	−3	
	RxG_JSM	$P_{\text{OUT}} = 28.25 \text{ dBm}$	—	—	−6	
Power Added Efficiency	PAELOW	$P_{\text{OUT}} = 7.0 \text{ dBm}$	10	13.5	—	%
	PAEMED	$P_{\text{OUT}} = 17.0 \text{ dBm}$	22	28	—	
	PAEHIGH	$P_{\text{OUT}} = 28.25 \text{ dBm}$	45	48	—	
Total Supply Current	ICC_LOW	$P_{\text{OUT}} = 7.0 \text{ dBm}$	—	44	60	mA
	ICC_MED	$P_{\text{OUT}} = 17.0 \text{ dBm}$	—	118	150	
	ICC_HIGH	$P_{\text{OUT}} = 28.25 \text{ dBm}$	—	410	436	
Quiescent Current	IQ_LOW	Low Power Mode	—	23	—	mA
	IQ_MED	Medium Power Mode	—	34	—	
Enable Control Current	IEN	—	—	20	40	μA
Mode Control Current	IMODE0	—	—	20	40	μA
	IMODE1	—	—	20	40	
Total Supply Current in Power Down Mode	IPD	$V_{\text{CC}} = 4.5 \text{ V}$ $V_{\text{EN}} = \text{Low}$ $V_{\text{MODE0}} = \text{Low}$ $V_{\text{MODE1}} = \text{Low}$	—	1	10	μA
ICC1 Current	ICC1_HIGH	—	—	—	10	mA
Adjacent Channel Leakage power Ratio ¹	5 MHz offset	ACLR5	$P_{\text{OUT}} = 7.0 \text{ dBm}$	—	−45	dBc
			$P_{\text{OUT}} = 17.0 \text{ dBm}$	—	−45	
			$P_{\text{OUT}} = 28.25 \text{ dBm}$	—	−42	
	10 MHz offset	ACLR10	$P_{\text{OUT}} = 7.0 \text{ dBm}$	—	−65	
			$P_{\text{OUT}} = 17.0 \text{ dBm}$	—	−61	
			$P_{\text{OUT}} = 28.25 \text{ dBm}$	—	−56	

Table 4. [continued] **Electrical Specifications for Nominal Operating Conditions**
Per Table 2 over dynamic range up to 28.25 dBm output power for STC1 modulation, unless otherwise specified.

Characteristics	Symbol	Condition	Minimum	Typical	Maximum	Unit
Adjacent Channel Power Ratio ^{3,4,5}	1.25 MHz offset	ACPR1	P _{OUT} = 27.75 dBm	—	–49.0	dBc
	1.98 MHz offset	ACPR2		—	–56.0	
Harmonic Suppression	Second	f _{o2}	P _{OUT} ≤ 28.25 dBm	—	–53.0	dBc
	Third	f _{o3}		—	–50.0	
Tx Noise in Rx Bands ⁵	Rx Band 1		2110 MHz–2170 MHz	—	—	dBm/Hz
	GPS Rx		1574 MHz–1577 MHz	—	—	
	ISM Rx		2400 MHz–2483.5 MHz	—	—	
EVM	EVM1	P _{OUT} = P _{OUT_MAX}	—	—	3.35	%
	EVM2	P _{OUT} = P _{OUT_MAX} – 3	—	—	2.50	
Rise / Fall Time	DC	TON_DC	—	—	5.0	μs
		TOFF_DC	—	—	5.0	
	RF	TON_RF	—	—	0.5	
		TOFF_RF	—	—	0.5	
Coupling Factor	CPL	P _{OUT} = P _{OUT_MAX}	–22	–20	–18	dB
CPL_OUT / P _{OUT} Power Ratio Variation Over Output VSWR		2.5:1 VSWR at P _{OUT} all VSWR phases CPL_IN 50 Ω terminated	—	±0.40	—	dB
Daisy-chain	VSWR	CPL_IN and CPL_OUT ports 698 MHz to 2620 MHz V _{EN} = Low	—	—	1.4:1	
	Insertion Loss	CPL_IN to CPL_OUT ports 698 MHz to 2620 MHz V _{EN} = Low	—	—	0.3	dB
Input Voltage Standing Wave Ratio	VSWR	—	—	1.2:1	1.8:1	—
Stability (Spurious output) ⁵	S	6:1 VSWR All phases	—	—	–70	dBc
Ruggedness – no damage ^{2,5}	Ru	P _{OUT} ≤ 28.25 dBm	10:1	—	—	VSWR

¹ ACLR is expressed as a ratio of total adjacent power to WCDMA modulated in-band, both measured in 3.84 MHz bandwidth at specified offsets.

² All phases, time = 10 seconds.

³ ACPR is specified per IS95 as the ratio of the total in-band power (1.23 MHz BW) to adjacent power in a 30 kHz BW.

⁴ For CDMA2000 test configured as [PCD at –7.40 dB, DCCH–9600 bps at –15.35 dB; SCH0–9600 bps at –15.63 dB] and other test configurations that yield a peak-to-average up to 4.02 dB for CCDF = 1%, up to 1 dB power back off from the maximum listed for IS95 may be required to meet specified maximum ACP performance under worst-case conditions.

⁵ Over conditions specified in Table 2

Table 5. Standard Test Configuration – STC1 WCDMA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	–6.547
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	–1.087

Table 6. Standard Test Configuration – STC2 HSDPA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	12/15	—	—	—	—	–7.095
DPDCH	60 kbps	16	64	I	—	15/15	—	—	—	–5.157
HS-DPCCH	15 kbps	64	256	Q	—	—	24/15	—	—	–3.012

Table 7. Standard Test Configuration – STC3 HSUPA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	8/15	—	—	—	—	–19.391
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	–13.931
HS- DPCCH	15 kbps	64	256	Q	—	—	8/15	—	—	–19.391
E-DPCCH	15 kbps	1	256	I	—	—	—	10/15	—	–17.338
E-DPDCH	960 kbps	2	4	I	—	—	—	—	71.5/15	–0.371

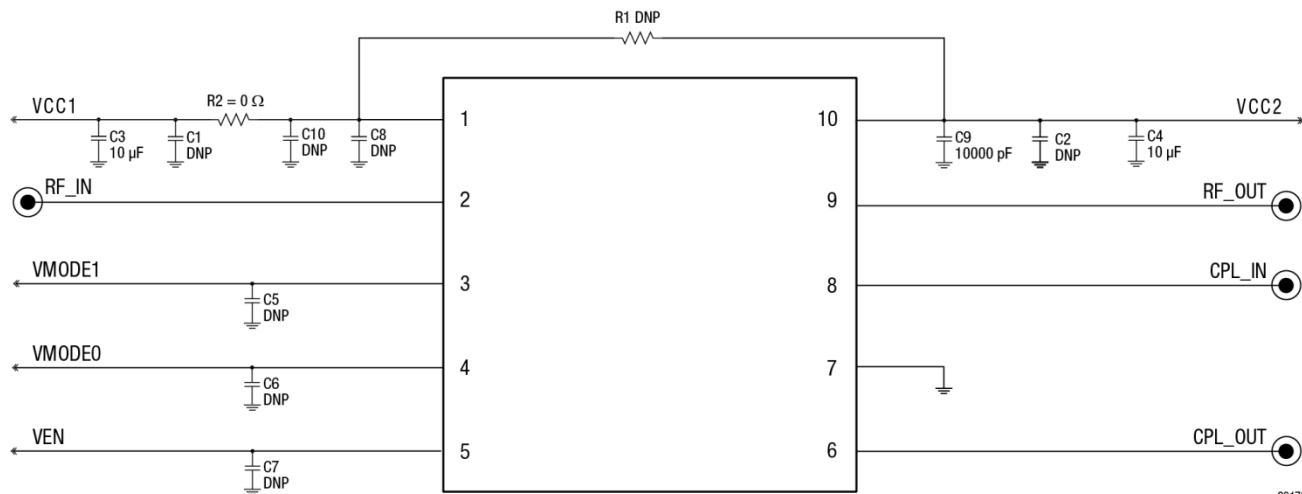
Table 8. Standard Test Configuration – STC4 HSUPA Mode

Parameter	Level	Spread Code	Spread Factor	I/Q	β_c	β_d	β_{hs}	β_{ec}	β_{ed}	Relative Power (dB)
DPCCH	15 kbps	0	256	Q	6/15	—	—	—	—	–12.499
DPDCH	960 kbps	1	4	I	—	15/15	—	—	—	–4.540
HS- DPCCH	15 kbps	64	256	Q	—	—	2/15	—	—	–22.041
E-DPCCH	15 kbps	1	256	I	—	—	—	12/15	—	–6.478
E-DPDCH	960 kbps	2	4	I	—	—	—	—	15/15	–4.425

Evaluation Board Description

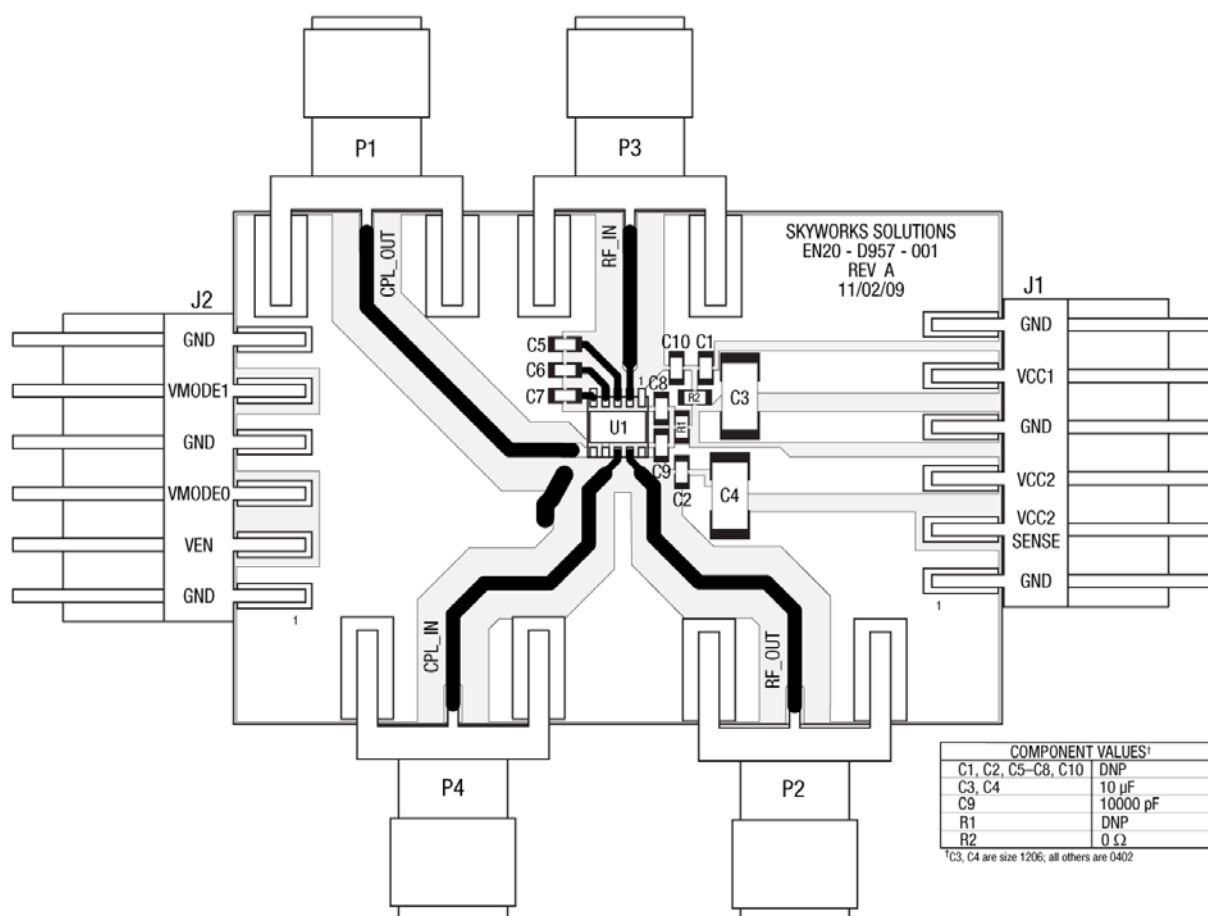
The evaluation board is a platform for testing and interfacing design circuitry. To accommodate the interface testing of the SKY77761-11, the evaluation board schematic and assembly diagrams are included for analysis and design. Figure 2 shows

the basic schematic of the board for the 1920 MHz to 1980 MHz range shown in Figure 3. Figure 4 is a schematic of the recommended application shown in Figure 5.



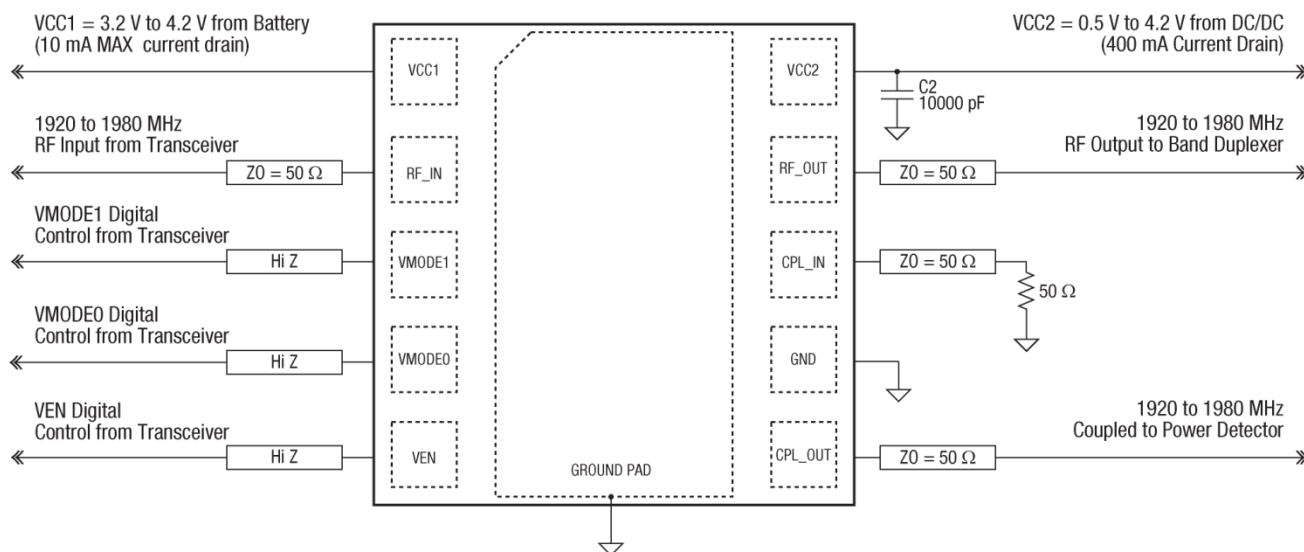
201706_002

Figure 2. Evaluation Board Schematic



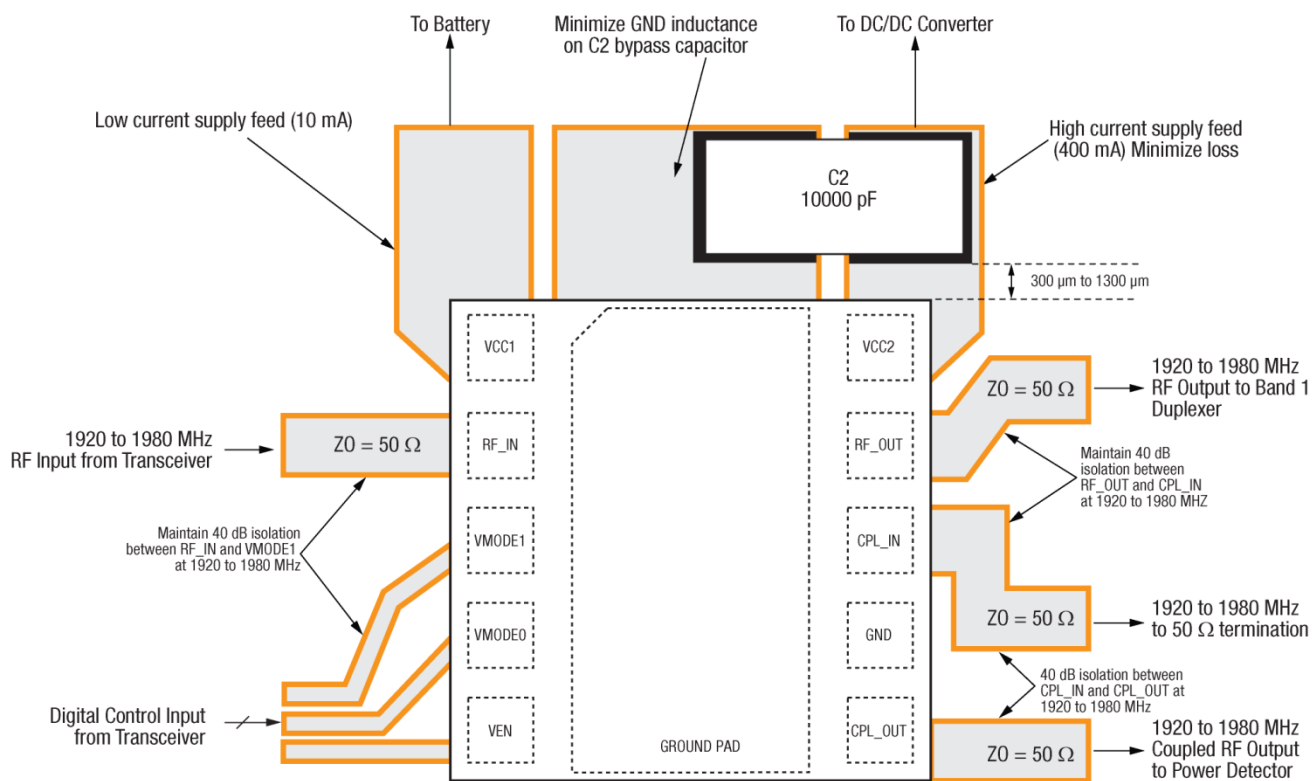
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Figure 3. Evaluation Board Assembly Diagram



201706_004

Figure 4. SKY77761-11 Schematic for Recommended Application Diagram



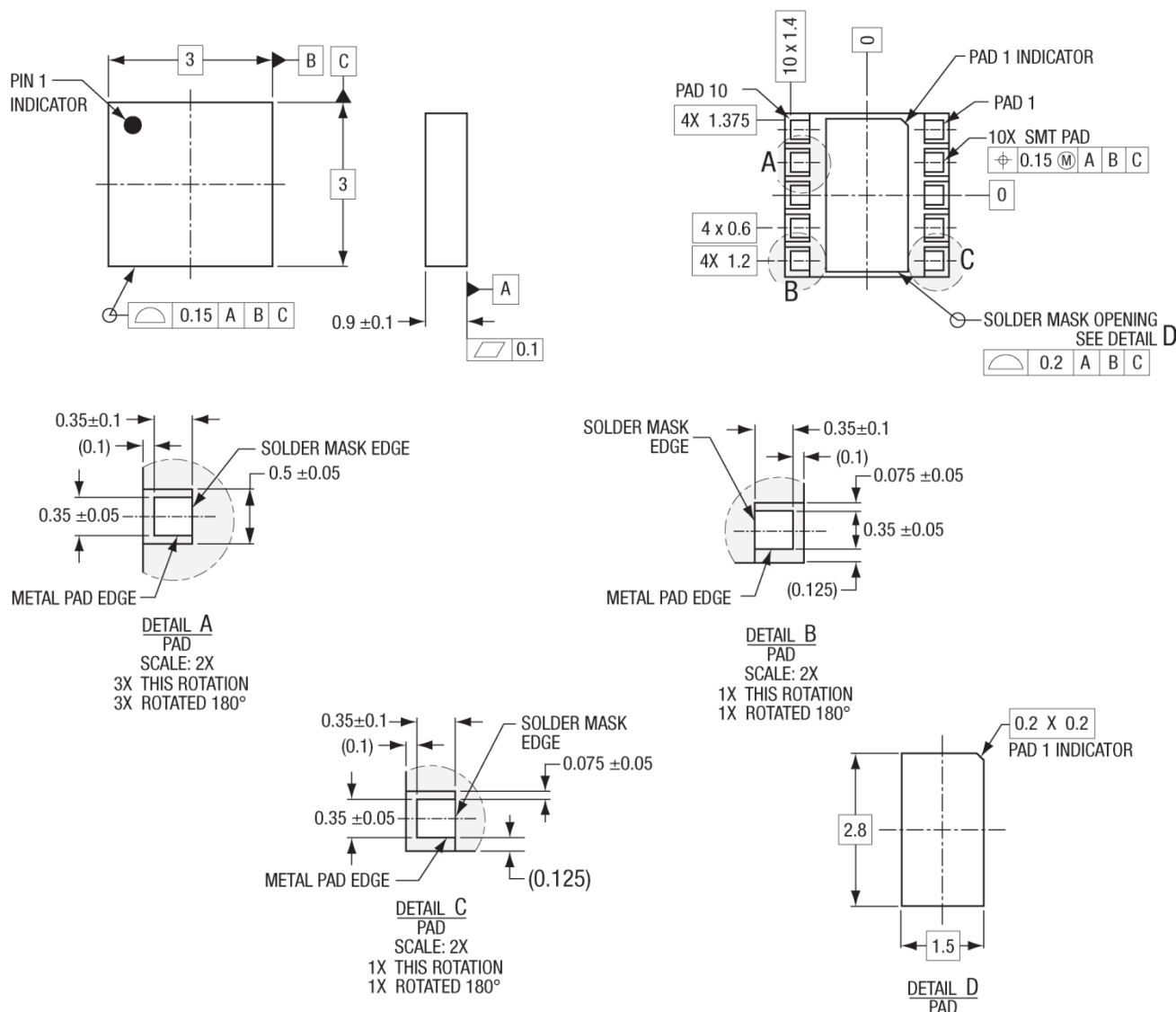
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Figure 5. SKY77761-11 Recommended Application Diagram

Package Dimensions

The SKY77761-11 is a multi-layer laminate base, overmold encapsulated modular package designed for surface mount solder attachment to a printed circuit board. Figure 6 is a mechanical drawing of the pad layout for this package. Figure 7 provides a

recommended phone board layout footprint for the PAM to help the designer attain optimum thermal conductivity, good grounding, and minimum RF discontinuity for the 50-ohm terminals.



NOTES: Unless otherwise specified.

1. Dimensioning and Tolerancing in accordance with ASME Y14.5M-1994
2. All dimensions are in millimeters.

DS_D804_77761 REV 1 2/08/12
201706 006

Figure 6. Dimensional Diagram for 3 mm x 3 mm x 0.9 mm Package – SKY77761-11 Specific

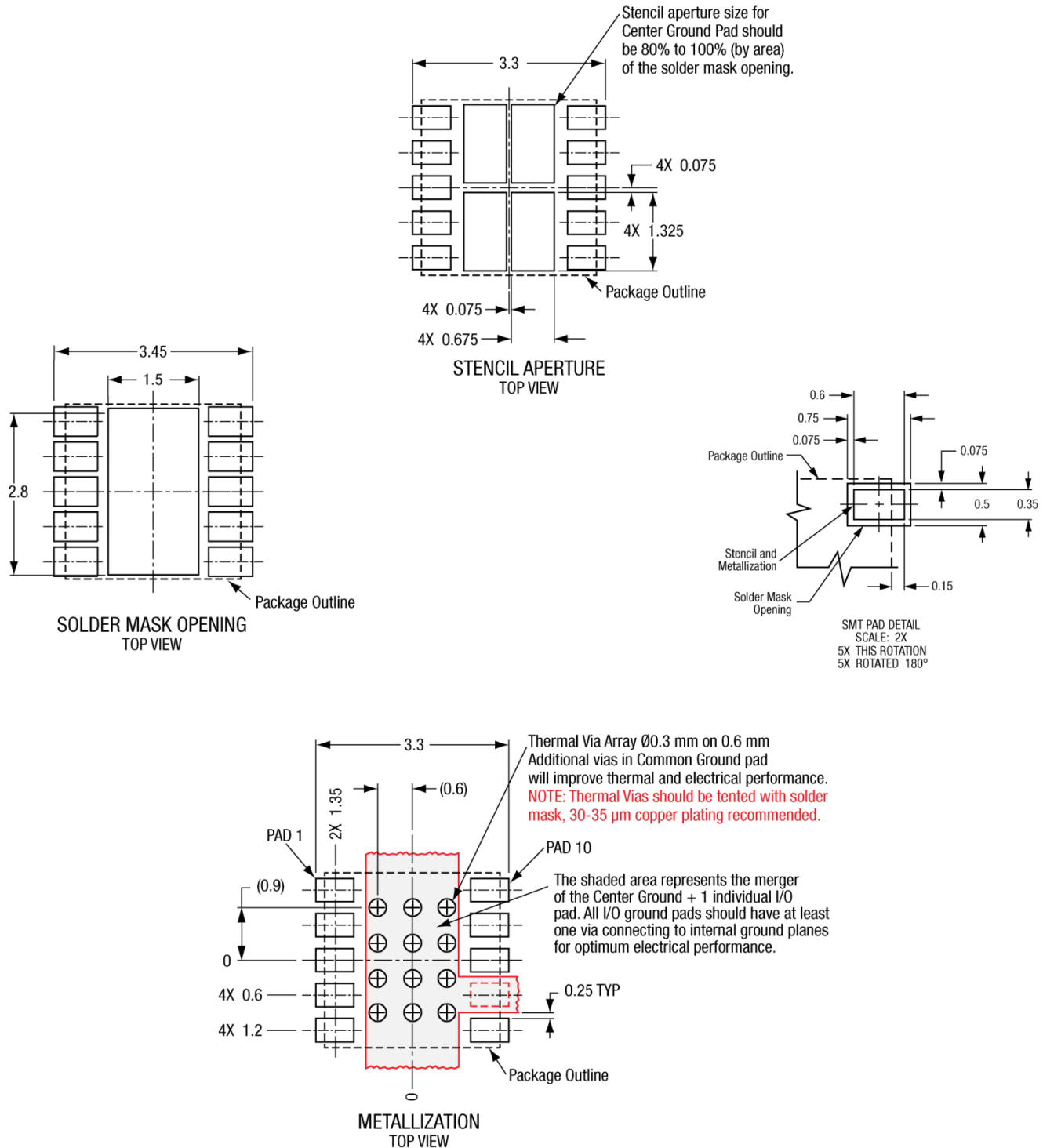
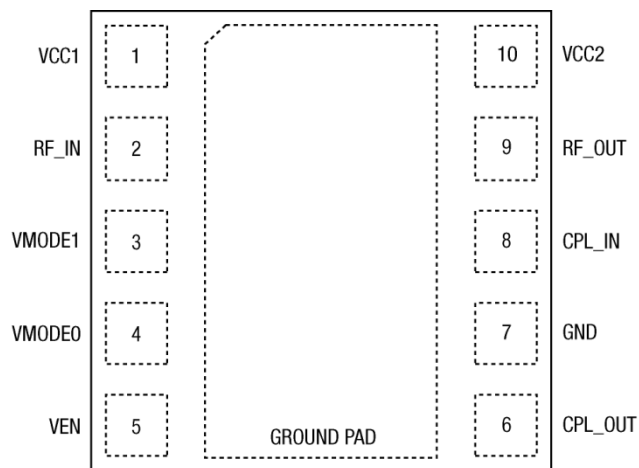


Figure 7. Phone PCB Layout Diagram – 3 mm x 3 mm, 10-Pad Package – SKY77761-11

DS00109-1 REV 1 7/01/09
201706_007

Package Description

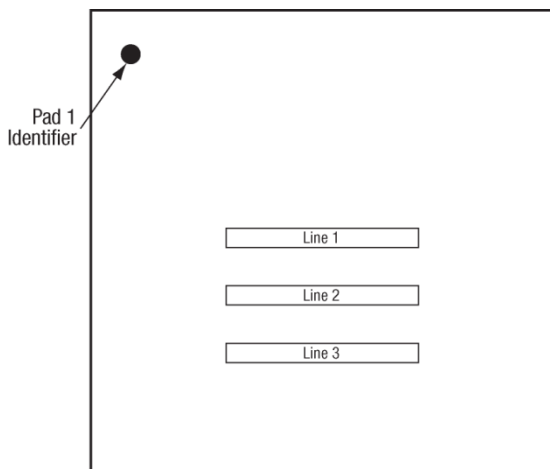
Figure 8 shows the pad functions and the pad numbering convention, which starts with pad 1 in the upper left and increments counter-clockwise around the package. Typical case markings are illustrated in Figure 9.



Pad layout as seen from Top View looking through the package.
GROUND PAD is package underside.

201706_008

Figure 8. SKY77761-11 Pad Names and Configuration (Top View)



NOTE: Lines 1, 2, 3 have a maximum of 7 characters
Line 1 = Part Number and Version
Line 2 = Lot Number
Line 3 = Year–Week–Country Code (MX)

201706_009

Figure 9. Typical Case Markings

Package Handling Information

Because of its sensitivity to moisture absorption, this device package is baked and vacuum-packed prior to shipment. Instructions on the shipping container label must be followed regarding exposure to moisture after the container seal is broken,

otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SKY77761-11 is capable of withstanding an MSL3/260 °C solder reflow. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. If the part is attached in a reflow oven, the temperature ramp rate should not exceed 3 °C per second; maximum temperature should not exceed 260 °C. If the part is manually attached, precaution should be taken to insure that the part is not subjected to temperatures exceeding 260 °C for more than 10 seconds. For details on attachment techniques, precautions, and handling procedures recommended by Skyworks, please refer to Skyworks Application Note: *PCB Design and SMT Assembly/Rework*, Document Number 101752. Additional information on standard SMT reflow profiles can also be found in the JEDEC Standard J-STD-020.

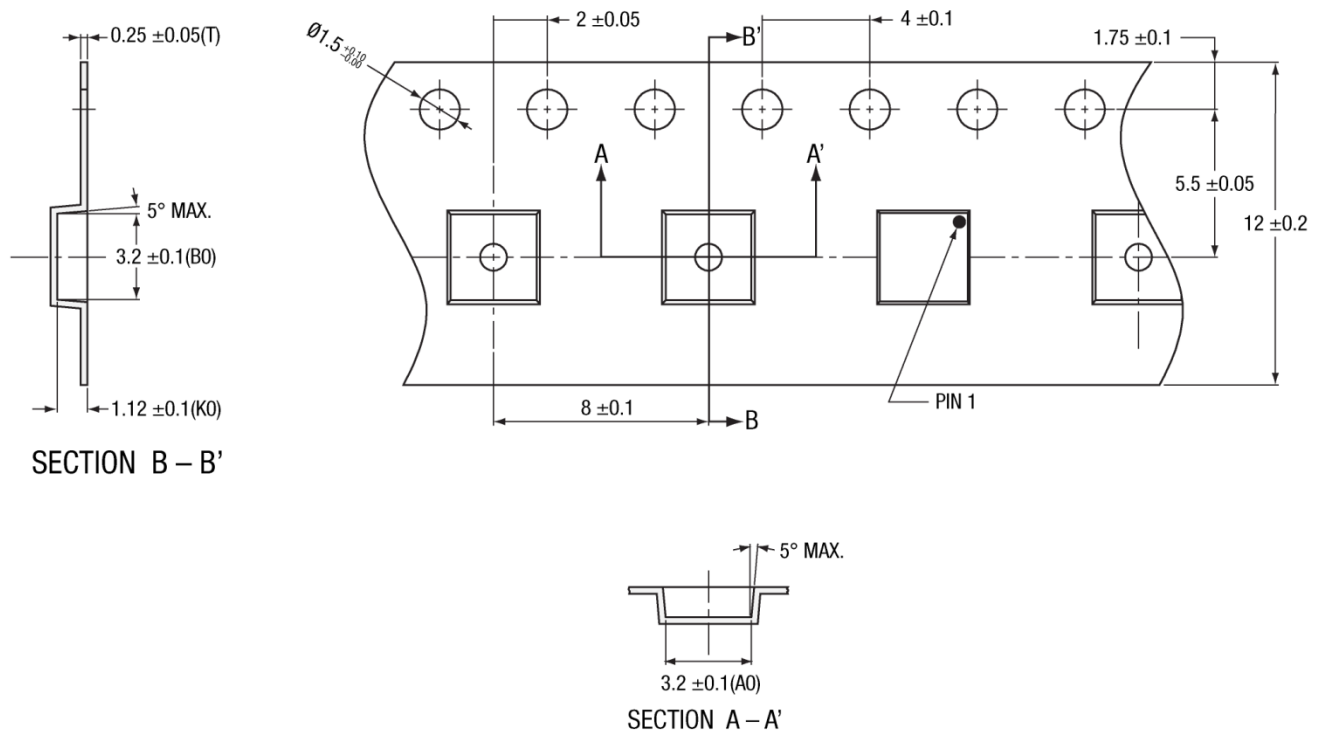
Production quantities of this product are shipped in the standard tape-and-reel format (Figure 10).

Electrostatic Discharge (ESD) Sensitivity

The SKY77761-11 meets class 1C JESD22-A114 Human Body Model (HBM), class IV JESD22-C101 Charged-Device Model (CDM), and class A JESD22-A115 Machine Model (MM) electrostatic discharge (ESD) sensitivity classification.

To avoid ESD damage, both latent and visible, it is very important that the product assembly and test areas follow the ESD handling precautions listed below.

- Personnel Grounding
 - Wrist Straps
 - Conductive Smocks, Gloves and Finger Cots
 - Antistatic ID Badges
- Protective Workstation
 - Dissipative Table Top
 - Protective Test Equipment (Properly Grounded)
 - Grounded Tip Soldering Irons
 - Solder Conductive Suckers
 - Static Sensors
- Facility
 - Relative Humidity Control and Air Ionizers
 - Dissipative Floors (less than 1,000 MΩ to GND)
- Protective Packaging and Transportation
 - Bags and Pouches (Faraday Shield)
 - Protective Tote Boxes (Conductive Static Shielding)
 - Protective Trays
 - Grounded Carts
 - Protective Work Order Holders



NOTES:

1. CARRIER TAPE IS BLACK CONDUCTIVE POLYCARBONATE OR POLYSTYRENE.
2. COVER TAPE IS TRANSPARENT AND CONDUCTIVE.
3. ESD-SURFACE RESISTIVITY IS $\leq 1 \times 10^{10}$ OHMS/SQUARE PER EIA, JEDEC TNR SPECIFICATION.
4. 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE: ± 0.2 mm
5. A0 & B0 MEASURED ON PLANE 0.3 mm ABOVE THE BOTTOM OF THE POCKET.
6. ALL DIMENSIONS ARE IN MILLIMETERS.

CARRIER TAPE OVERMOLD MCM / RFLGA $3 \times 3 \times 0.75 / 0.90$ mm BODY SIZE -108A
201075_008

Figure 10. Dimensional Diagram for Carrier Tape Body Size 3 mm x 3 mm x 0.75 / 0.90 mm – MCM

Ordering Information

Product Name	Order Number	Evaluation Board Part Number
SKY77761 Power Amplifier Module	SKY77761-11	EN20-D957-001 REV A

Revision History

Revision	Date	Description
A	December 20, 2011	Initial Release – Advance Information
B	February 7, 2012	Revise: Figure 1; Tables 1, 4 Add: Figures 4, 5
C	March 8, 2012	Revise: Figures 2–7; Table 4 footnote 5
D	May 2, 2012	Revise: Change Data Sheet status from ADVANCE to PRELIMINARY; include -11 to all occurrences of part number; Features list (p1); Description (p1); Tables 2, 4
E	August 10, 2012	Revise: Change Data Sheet status from PRELIMINARY to FINAL; Title, Applications list (p1); Tables 2, 4

References

Skyworks Application Note: PCB Design and SMT Assembly/Rework, Document Number 101752.

Standard SMT Reflow Profiles: JEDEC Standard J–STD–020

Electrostatic Discharge Sensitivity (ESD) Testing: JEDEC Standard, JESD22-A114 Human Body Model (HBM)

Electrostatic Discharge Sensitivity (ESD) Testing: JEDEC Standard, JESD22-A115 Machine Model (MM)

Electrostatic Discharge Sensitivity (ESD) Testing: JEDEC Standard, JESD22-C101 Charged Device Model (CDM).

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